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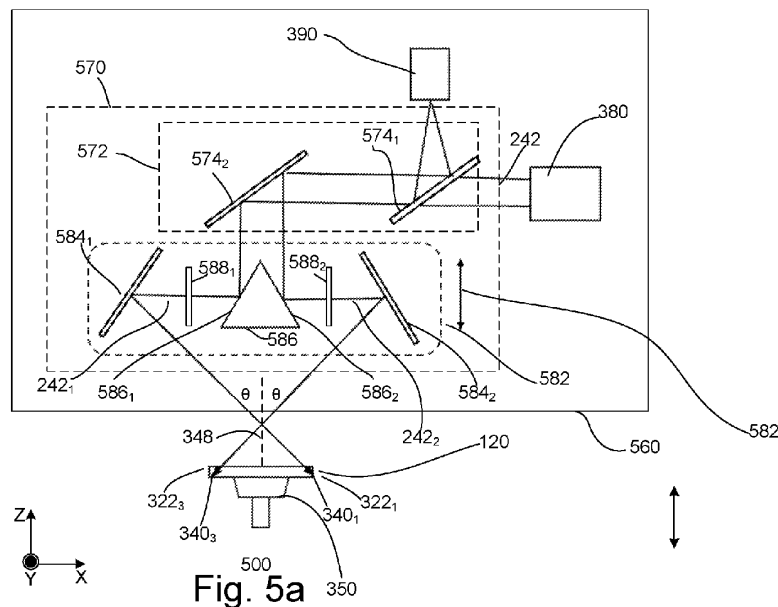
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(54) Title: SYSTEM AND METHOD FOR INSPECTING DEVICES FOR INTERNAL DEFECTS AT ABOUT SIDEWALLS
THEREOF CAUSED BY WAFER SINGULATION PROCESSES



(57) Abstract: Disclosed are systems and methods for inspecting dies to detect defects (internal and external) located in zones or regions of interest at sides (internal sidewalls) of singulated dies. In particular, the inspection can detect how far defects extend towards or beyond the seal ring of a die. Defects which extend close to or beyond the seal ring pose failure or potential failure risks. In addition, the inspection is configured for high-speed and accurate detection of defects in regions of interest of dies. High-speed inspection includes simultaneous, sequential or a combination of simultaneous and sequential inspection of the regions of interest.

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